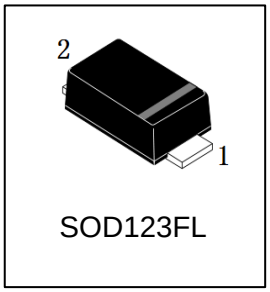
LMBR320FT1G thru LMBR3200FT1G

Schottky Barrier Rectifiers

Reverse Voltage 20 to 200V Forward Current 3.0A

FEATURES

* Plastic package has Underwriters Laboratory Flammability Classification 94V-0
* Low power loss,high efficiency
* For use in low voltage high frequency inverters, free wheeling,and polarity protection applications
* Guardring for over voltage protection
* High temperature soldering guaranteed: 260°C/10 seconds at terminals



We declare that the material of product is Haloggen free (green epoxy compound)

Mechanical Data

Case: SOD123-FL/MINI SMA molded plastic over sky die
Terminals: Plated leads, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.0155 g
Handling precautin:None

1.Electrical Characteristic

Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR 320FT1G	LMBR 330FT1G	LMBR 340FT1G	LMBR 350FT1G	LMBR 360FT1G	LMBR 380FT1G	LMBR 3100FT1G	LMBR 3150FT1G	LMBR 3200FT1G	Unit
device marking code		32	33	34	35	36	38	310	315	320	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TC = 75°C	$I_{F(AV)}$	3.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	80									A
Typical thermal resistance (Note 1)	$R\theta J_A$	170									°C/W
Operating junction temperature range	T_J	–55 to +150									°C
storage temperature range	T_{STG}	–65 to +175									°C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR 320FT1G	LMBR 330FT1G	LMBR 340FT1G	LMBR 350FT1G	LMBR 360FT1G	LMBR 380FT1G	LMBR 3100FT1G	LMBR 3150FT1G	LMBR 3200FT1G	Unit
Maximum instantaneous forward voltage at 3.0A	V_F	0.50			0.70		0.85		0.9	0.92	V
Maximum DC reverse current at rated DC blocking voltage T_A = 25℃ Tj = 100℃	I_R	0.5 20									mA
Typical junction capacitance at 4.0V, 1MHz	C_J	160									PF

NOTES:

1. 8.0mm2 (.013mm thick) land areas

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2.Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

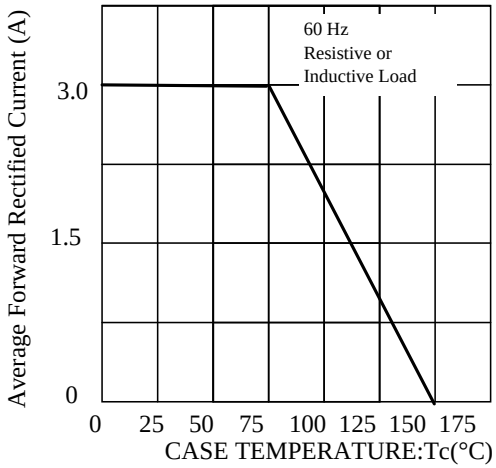


Fig. 2 – Maximum Non-repetitive Peak Forward Surge Current

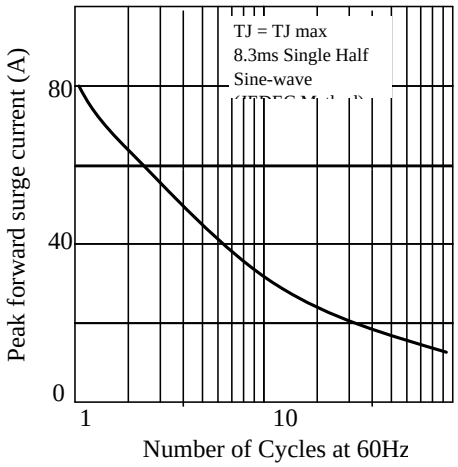


Fig 3. – Typical Instantaneous Forward Characteristics

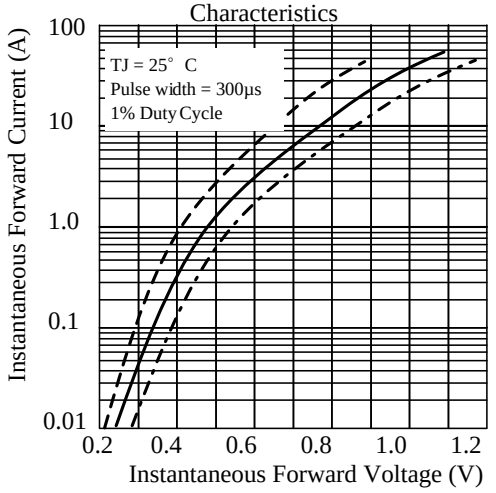


Fig 4. – Typical Reverse Characteristics

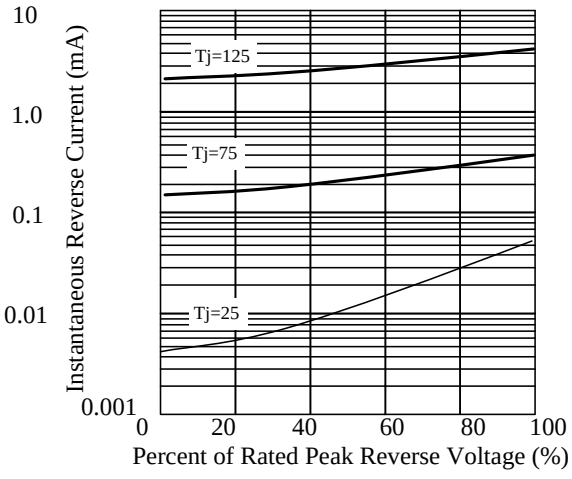


Fig 5. – typical transient thermal impedance

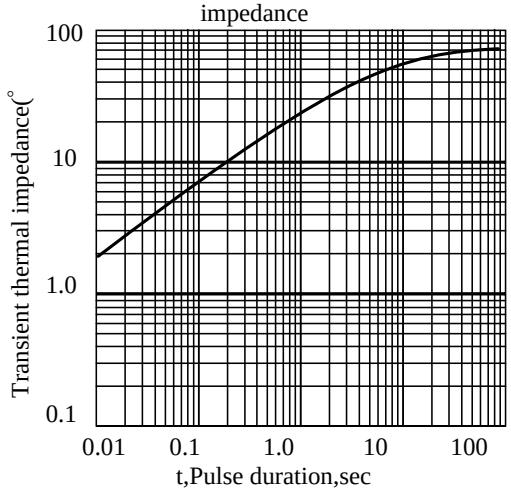
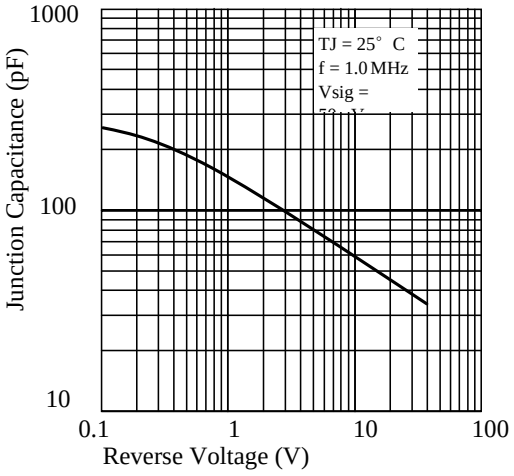
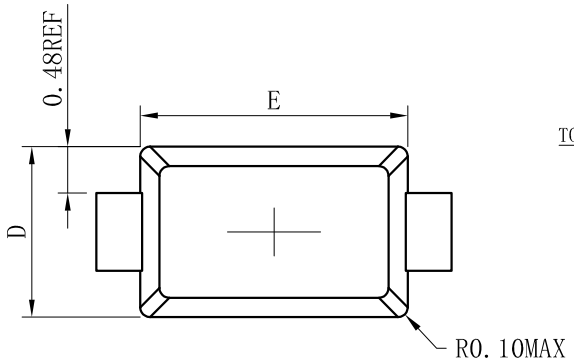


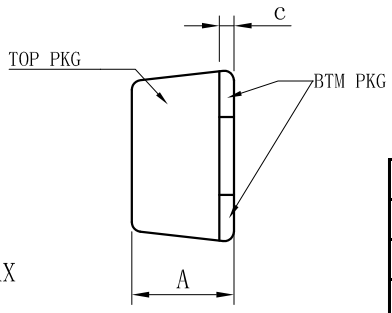
Fig 6. – Typical Junction Capacitance



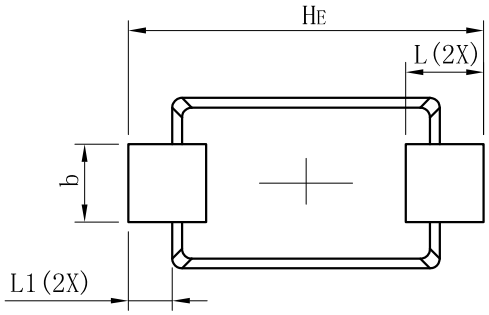
3.OUTLINE AND DIMENSIONS



TOP VIEW



SIDE VIEW



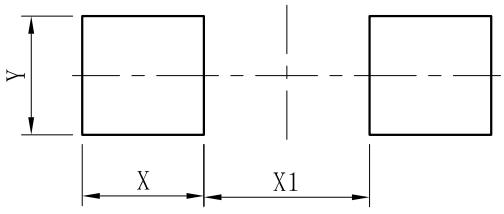
BOTTOM VIEW

SOD123FL			
DIM	MIN	NOR	MAX
A	0.90	1.05	1.15
b	0.75	0.80	0.95
L	0.80REF.		
E	2.60	2.75	2.90
D	1.60	1.75	1.90
HE	3.50	3.65	3.80
c	0.12	0.17	0.22
L1	0.45REF.		
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um

4.SOLDERING FOOTPRINT



DIM	(mm)
X	1.20
Y	1.10
X1	2.00

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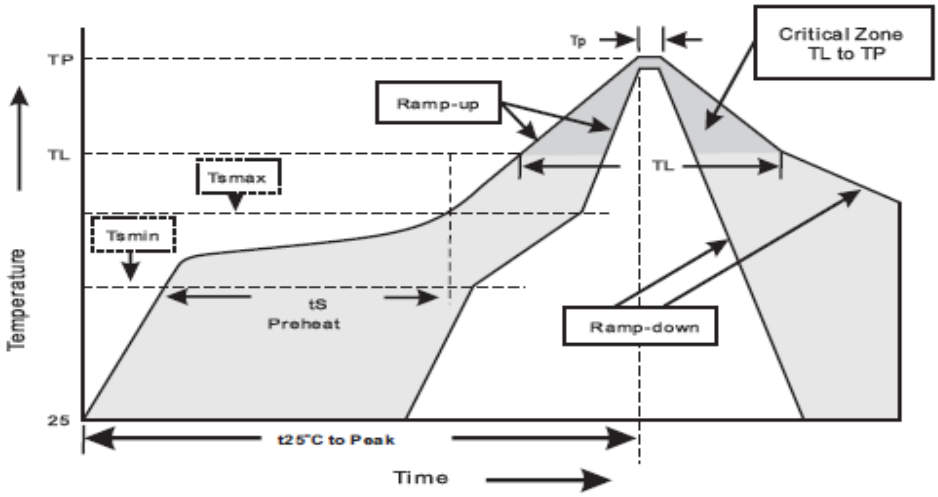
5.Suggested thermal profile for soldering process

1. Storage environment：Temperature=5~40℃ Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3℃/sec
Preheat - Temperature Min(Tsmin) - Temperature Max(Tsmax) - Time(min to max)(t_s)	 150℃ 200℃ 60~120sec
Tsmax to T_L - Ramp-up Rate	 <3sec
Time maintained above: - Temperature (T_L) - Time(t_L)	 217℃ 60-260sec
Peak Temperature(T_P)	255 -0/+5℃
Time within 5℃ of actual Peak Temperature(T_P)	10~30sec
Ramp-down Rate	<6℃/sec
Time 25℃ to Peak Temperature	<6minutes

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6.High reliability test capabilities

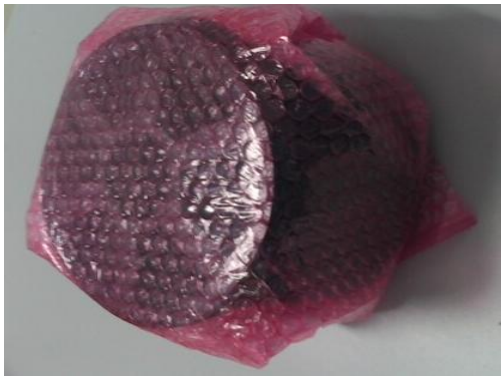
Item Test	Condition	Reference
Solder Resistance	at 260±5℃ for 10±2sec immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031
Solderability	at 245±5℃ for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V_R=80% rate at T_j=150℃ for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current T_A=25℃ for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T_A=25℃，I_F=I_O On state:power on for 5 min. Off state:power off for 5 min. on and off for 500 cycles	MIL-STD-750D METHOD-1036
Pressure Cooker	15P_{SIG} at T_A=121℃ for 4hrs	JESD22-A102
Temperature Cycling	-55℃ to +125℃ dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0℃ for 5min. Rise to 100℃ for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T_A=85℃，R_H=85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 175℃ for 1000hrs	MIL-STD-750D METHOD-1031

8.1.2 Label position and QA stamp position.(Empty area) 标签张贴位置及QA印章位置。（印章盖在标签空白区

7英寸卷盘标签张贴及QA印章位置

13英寸卷盘标签张贴及QA印章位置

8.1.3 Ensure direction In the same reel. The same steel coil plate direction，With antistatic bubble to package reel。Refer to the below picture.
同一箱内的卷盘方向一致,用防静电泡沫对卷盘进行包裹。



7英寸卷盘防静电泡沫包裹

13英寸卷盘防静电泡沫包裹

8.1.4 Put in the antistatic packing box after packaged reels. And QA stamp on the box label .
将包装好的卷盘放入防静电纸箱中，并在盒标签上盖章。

7 英寸卷盘内盒及标签

13 英寸卷盘内盒及标签

8.1.5 Product use printing inner box. 产品使用LRC印字内箱。

7英寸卷盘内箱印字（侧面）

13英寸卷盘内箱印字（正面）

8.1.6 Inner box packing quantity requirement.内盒包装数量要求。

Product Description	QTY
SOD123-FL	1-10Reels
SOD323-HE	1-10Reels
SMA-FL	1-7Reels
SMB-FL	1-4Reels

8.1.7 With transparent tape sealing. 透明胶带封箱。

7英寸内箱封盒

13英寸内箱封盒

8.1.8 Outer box size and packing quantity requirement,外箱尺寸及包装数量要求。

Product Description	卷盘尺寸	Height（H）	Width（W）	Length（L）	Max. Qty
Power Device	7 英寸	410mm	400mm	445mm	12
Power Device	13 英寸	410mm	400mm	445mm	5

7 英寸卷盘产品装箱

13 英寸卷盘产品装箱

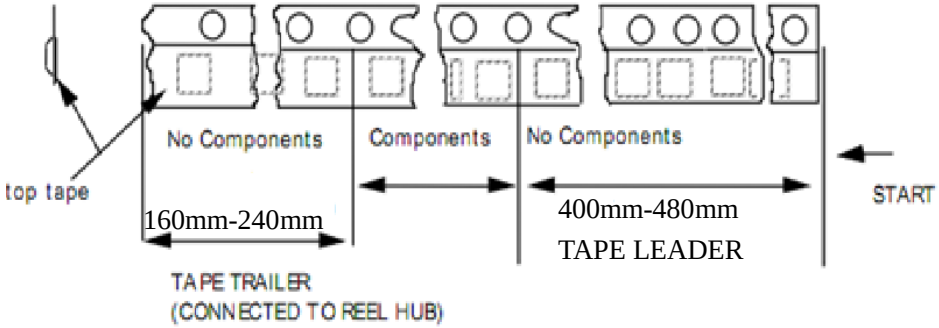
8. 2 Standard Products Taping Specification
标准产品编带规范

8.2.1 Tape length of no component
空带长度说明

Taping leader length 引导部分：440mm±40mm ， Tape trailer 尾部：200mm±40mmt

Figure 4

Tape Ends For Finished Goods Reel



8.2.2 Component packaging orientation: The cathode lead is close to the carrier tape's index hole.
产品放置方向：印阴极带引脚邻近载带索引孔

8.2.3 Tape enwind orientation

编带缠绕方向要求